To the Director of the U.S. Patent and Trademark Office

1. Name of conveying party(ies):
   Jin Young LEE (07/22/2008), Gang Woon HEO (07/22/2008), Young Min Yun (07/22/2008), and Bong Young LEE (07/22/2008)
   Additional name(s) of conveying party(ies) attached? [X] No

2. Name and address of receiving party(ies):
   Name: TPC MECHATRONICS CORP.
   Internal Address: 
   Street Address: 111-84 Hwagok 5-dong
   Gangseo-gu
   City: Seoul
   State: 
   Country: Republic of Korea
   Zip: 157-873
   Additional name(s) & address(es) attached? [X] No

3. Nature of conveyance/Execution Date(s):
   Execution Date(s): in parentheses after inventor name
   Assignment [X]
   Merger
   Change of Name
   Security Agreement
   Joint Research Agreement
   Government Interest Assignment
   Executive Order 9424, Confirmatory License
   Other

4. Application or patent number(s):
   PATENT NO.
   A. Patent Application No.(s)
      NATIONAL STAGE OF PCT/KR2006/003061
   Additional numbers attached? [X] No
   B. Patent No.(s)
      12/223,736

5. Name and address to whom correspondence concerning document should be mailed:
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6. Total number of applications and patents involved:
   [ ] 1

7. Total fee (37 CFR 1.21(h) & 3.41) $ 40.00
   Authorized to be charged by credit card [X]
   Authorized to be charged to deposit account
   Enclosed
   None required (government interest not affecting title)

8. Payment Information
   a. Credit Card
      Last 4 Numbers
      Expiration Date
   b. Deposit Account Number
      Authorized User Name Bryant E. Wade
      08-0750

9. Signature:
   Bryant E. Wade - 40,344
   Name of Person Signing
   Signature
   August 7, 2008
   Date

Total number of pages including cover sheet, attachments, and documents: 3

PATENT REEL: 021388 FRAME: 0186
ASSIGNMENT

WHEREAS, the undersigned, hereinafter referred to as Assignor, has invented:

CIRCUIT BOARD FOR A SOLENOID VALVE MANIFOLD

for which Assignor is about to make or has made United States or International application for patent

(a) ☐ executed on even date preparatory to filing (each inventor should sign this Assignment on the same day as he/she signs the Declaration and Power of Attorney);

(b) ☐ executed on _____, _____, ____; or

(c) ☒ filed on August 4, 2006, and assigned Serial No. _____ or PCT International Application No. PCT/KR2006/003061; and

WHEREAS, TPC MECHATRONICS CORP., residing at 111-84 Hwagok 5-dong, Gangseo-gu, Seoul 157-873, Republic of Korea, hereinafter referred to as Assignee, is desirous of acquiring all right, title, and interest therein:

NOW, THEREFORE, for good and valuable consideration, the receipt and adequacy whereof is hereby acknowledged, Assignor agrees to, and hereby does, sell, assign and transfer unto Assignee and its successors in interest, the full and exclusive right, title and interest in the United States of America and throughout the world, including the right to claim priority under the laws of the United States, the Paris Convention, and any foreign countries, to the invention as described in the aforesaid application and all United States Letters Patent which may be granted therefore, and all divisions, continuations, reissues, reexaminations and extensions thereof, these rights, title and interest to be held and enjoyed by Assignee to the full end of the term for which the Letters Patent are granted and any extensions thereof as fully and entirely as the same would have been held by Assignor had this assignment and sale not been made, and the right to sue for, and recover for past infringements of, or liabilities for, any of the rights relating to any of the applications or patents resulting therefrom;

Assignor hereby covenants and agrees to execute all instruments or documents required or requested for the making and prosecution of any applications of any type for patent in the United States and in all foreign countries including, but not limited to, any provisional, continuation, continuation-in-part, divisional, renewal or substitute thereof, and as to letters patent any reissue, reexamination, or extension thereof, and for litigation regarding, or for the purpose of protecting title and to the said invention, the United States application for patent, or Letters Patent therefor, and to testify in support thereof, for the benefit of Assignee without further or other compensation than that above set forth;

Assignor hereby covenants that no assignment, sale, license, agreement or encumbrance has been or will be entered into which would conflict with this Assignment; and

Assignor hereby requests the United States Patent and Trademark Office to issue the Letters Patent of the United States of America to Assignee, and requests that any official of any country or countries foreign to the United States, whose duty it is to issue or grant patents and applications as aforesaid, to issue the Letters Patent, Utility Model Registration or Inventor's Certificate to Assignee.

The undersigned hereby grant(s) the law firm of Hamess, Dickey & Pierce, P.L.C. the power to insert on this Assignment any further identification which may be necessary or desirable in order to comply with the rules of the U.S. Patent and Trademark Office for recordation of this document.
ASSIGNMENT

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Inventor: Jin Young LEE
Dated: 2008. 7. 22

Gang Woon Heo

Inventor: Gang Woon HEO
Dated: 2008. 7. 22

Young Min YUN

Inventor: Young Min YUN
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Bong Young Lee

Inventor: Bong Young LEE
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